

Chemical content 74AHC2G126DP-Q100



Type number	Package	Package description	Total product weight
74AHC2G126DP-Q100	SOT505-2	TSSOP8	21.05094 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935300744125	3	1	260	30 s	1	240	20 s	3	Suzhou, China; Ayutthaya, Thailand; Nijmegen, Netherlands; Bangkok, Thailand	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.01982	80.10000	0.09414
	Polymer	Resin system	Proprietary	0.00492	19.90000	0.02339
		subTotal		0.02474	100.00000	0.11753
Die	Doped silicon	Silicon (Si)	7440-21-3	0.12318	100.00000	0.58513
		subTotal		0.12318	100.00000	0.58513
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	8.50930	97.47000	40.42241
		Iron (Fe)	7439-89-6	0.20952	2.40000	0.99532
		Phosphorous (P)	7723-14-0	0.00262	0.03000	0.01244
		Zinc (Zn)	7440-66-6	0.00873	0.10000	0.04147
		subTotal		8.73017	100.00000	41.47164
Mould Compound	Additive	Non hazardous	Proprietary	0.56518	4.70000	2.68484
	Filler	Silica fused	60676-86-0	9.49991	79.00000	45.12819
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	0.72151	6.00000	3.42746
	Pigment	Carbon black	1333-86-4	0.02405	0.20000	0.11425
	Polymer	1,4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	0.48101	4.00000	2.28497
		Non hazardous	Proprietary	0.49303	4.10000	2.34210
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.24050	2.00000	1.14249
	subTotal		12.02520	100.00000	57.12430	
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00360	3.00000	0.01708
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.11062	92.30000	0.52549
		Palladium (Pd)	7440-05-3	0.00372	3.10000	0.01765
		Silver (Ag)	7440-22-4	0.00192	1.60000	0.00911
		subTotal		0.11985	100.00000	0.56933
Wire	Pure metal	Copper (Cu)	7440-50-8	0.02780	100.00000	0.13208
		subTotal		0.02780	100.00000	0.13208

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